

**PRODUCT FLOW SUMMARY  
TYPICAL DEI PLASTIC SMT PACKAGE**

<b>PROCESS DESCRIPTION</b>	<b>BURN-IN</b>	<b>STD</b>
<b>INCOMING WAFER INSPECTION</b>	YES	YES
<b>WAFER PROBE</b>	SAMPLE	SAMPLE
<b>WAFER SAW</b>	YES	YES
<b>2<sup>ND</sup> OPTICAL INSPECTION</b>	YES	YES
<b>DIE ATTACH</b>	YES	YES
<b>WIRE BOND</b>	YES	YES
<b>3<sup>RD</sup> OPTICAL INSPECTION</b>	YES	YES
<b>MOLD AND CURE</b>	YES	YES
<b>MARK (Ink or Laser)</b>	YES	YES
<b>MARK PERMANENCY (Ink)</b>	SAMPLE	SAMPLE
<b>LEAD FINISH</b>	YES	YES
<b>TRIM/FORM/SINGULATION</b>	YES	YES
<b>PACKAGE QC FINAL VISUAL AND LOT ACCEPTANCE</b>	YES	YES
<b>PRE-ELECTRICAL VISUAL INSPECTION</b>	YES	YES
<b>PRE BURN-IN ELECTRICAL TEST, ROOM/HOT/COLD</b>	100% ROOM & HOT, SAMPLE COLD	NO
<b>HTRB BURN-IN, 125C 160HR</b>	100%	NO
<b>ELECTRICAL TEST, ROOM TEMPERATURE</b>	100%	100%
<b>ELECTRICAL TEST, HOT TEMPERATURE</b>	100%	100%
<b>ELECTRICAL TEST, COLD TEMPERATURE</b>	0.65% AQL	0.65% AQL
<b>FINAL VISUAL AND COPLANAR INSPECTION</b>	100%	100%
<b>BAKE &amp; DRY PACK</b>	YES	YES
<b>PACK &amp; SHIP</b>	YES	YES